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Docket No: <u>112857-416</u>

U.S. DEPARTMENT OF COMMERCE Form **PTO-1595** RECOR U.S. Patent and Trademark Office (Rev. 03/01) OMB No. 0651-0027 (exp. 5/31/2002) To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): (1) Hideki Sakai (5) Tsuyonobu Hatazawa Name: Sony Corporation (2) Takashi Tomita Internal Address: __ (3) Ryosuke Takagi (4) Yusuke Suzuki Additional name(s) of conveying party(ies) attached? Yes x No 3. Nature of conveyance: Street Address: 7-35, Kitashinagawa, 6-Chome x Assignment Merger Shinagawa-ku Security Agreement Change of Name City: Tokyo Zip: 141-0001 Other ____ Country: Japan Additional name(s) & address(es) attached? Yes x No Execution Date(s): (1)(2) 03-19-04; (3) 03-25-04; and (4)(5) 03-22-04 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) 10/489,576 Additional numbers attached? Yes X No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved; 1 concerning document should be mailed: 7. Total fee (37 CFR 3.41).....\$\,\frac{40.00}{} Enclosed Thomas C. Basso Bell, Boyd & Lloyd LLC Authorized to be charged to deposit account P.O. Box 1135 8. Deposit account number: Chicago, Illinois 60690-1135 02-1818 DBYRNE 00000024 10489576 40.00 I (Attach duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Thomas C. Basso (46,541) April 1, 2004 Name of Person Signing Signature Date Total number of pages including cover sheet, attachments, and documents: 3

> Mail documents to be recorded with required cover sheet information to: Commissioner for Patents, Mail Stop Assignments, P.O. Box 1450, Alexandria, VA 22313-1450

Docket Number:	· .

ASSIGNMENT

*	WHEREAS, I, as a below	named inventor, residing	at the address	s stated next to my name, am a sole inventor (if
only one name	is listed below) or a joint in	ventor (if plural names are	listed below)	of certain new and useful improvements in
RELCELL	FUEL CELL			

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Application No. PCT/JP03/09480, International Filing Date: July 25, 2003

This assignment executed on the dates indicated below.

Hideki SAKAI		
Name of first or sole inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of first or sole inventor		
v Hideki Sakai	19/03/04	
Signature of first or sole inventor	Date of this assignment	

PATENT REEL: 015172 FRAME: 0794

Takashi TOMITA	
Name of second joint inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Kanagawa, Japan Residence of second joint inventor	4
Johnshi Jomita Signature of second joint inventor	Mar. 19 2004 Date of this assignment
Signature of second joint inventor	Date of this assignment
·	
Ryosuke TAKAGI	
Name of third joint inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of third joint inventor	/ / ,
V Ryosuce Takagn Signature of third joint inventor	Date of this assignment
Signature of third joint inventor	Date of this assignment
•	
. Vargadas CURTURT	
Yusuke SUZUKI Name of fourth joint inventor	Execution date of U.S. Patent Application
_	
Residence of fourth joint inventor	
Kanagawa, Japan Residence of fourth joint inventor V Yusuke Suguki Signature of fourth joint inventor	22/03/04
Signature of fourth joint inventor	Date of this assignment
Tsuyonobu HATAZAWA	
Name of fifth joint inventor Tokyo, Japan	Execution date of U.S. Patent Application
Residence of fifth joint inventor	
V Jangardi: Hitterinu M Signature of fifth Joint inventor	ZZ/03/04
Signature of fifth Joint inventor	Date of this assignment

RECORDED: 04/05/2004

PATENT REEL: 015172 FRAME: 0795